

Attracting Tomorrow



# Innovation in DC link for PCBs

DC link film capacitors in round case  
B32320I series



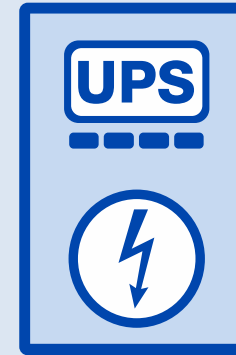
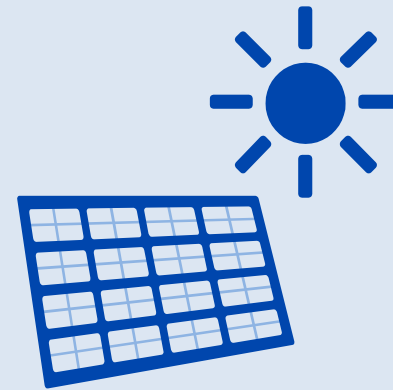
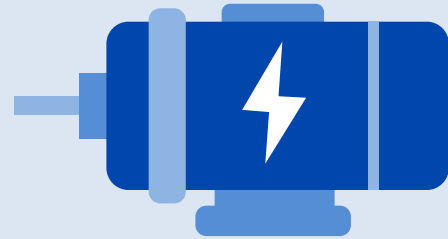
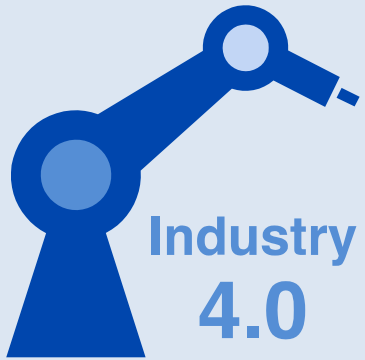
**TDK Electronics AG**  
Aluminum & Film Capacitors Business Group  
Munich, Germany  
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# Main applications

Industrial

Consumer



Industrial drives

Solar inverters

UPS

Aircon inverters

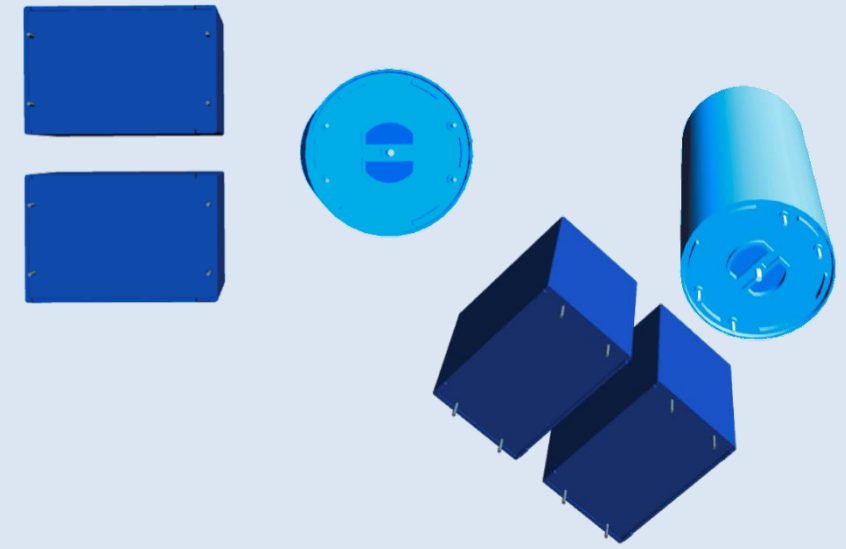
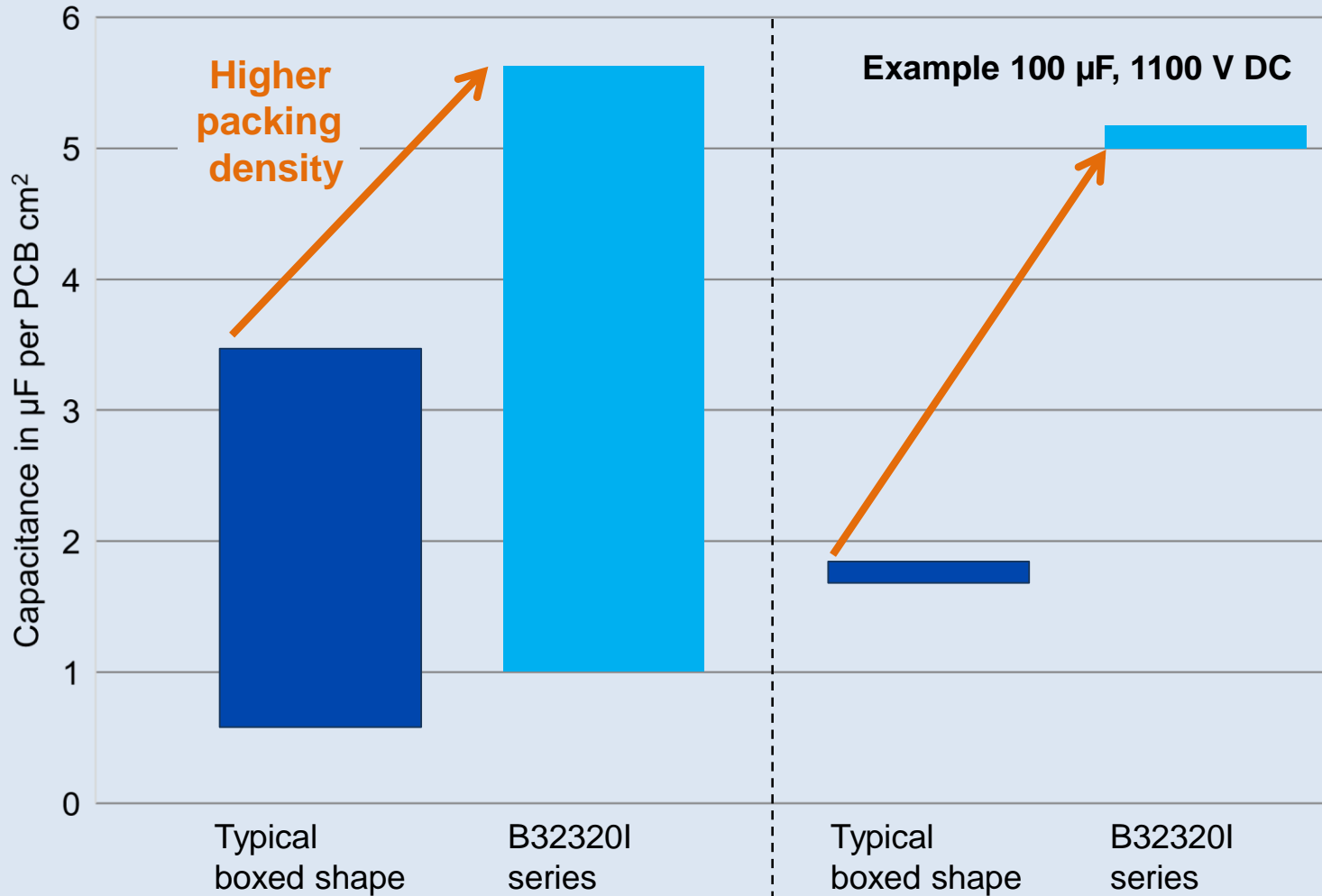
# Key advantages

- Up to 260  $\mu\text{F}$  in one unit
- Up to 100  $\mu\text{F}$  @ 1300 V DC
- **Small PCB footprint**
- High current capability
- Low ESR
- Complete the range on DC link film capacitors
- Temperature rating (hot spot)  
+85 °C without current derating  
+105 °C with current derating



| Type                    | B32320I  |          |           |           |
|-------------------------|----------|----------|-----------|-----------|
|                         | 450 V DC | 800 V DC | 1100 V DC | 1300 V DC |
| $V_R$ (105 °C)          | 450 V DC | 800 V DC | 1100 V DC | 1300 V DC |
| $C_R$ ( $\mu\text{F}$ ) |          |          |           |           |
| 6.5                     |          |          |           |           |
| 9.5                     |          |          |           |           |
| 15                      |          |          |           |           |
| 20                      |          |          |           |           |
| 21                      |          |          |           |           |
| 27                      |          |          |           |           |
| 30                      |          |          |           |           |
| 49                      |          |          |           |           |
| 50                      |          |          |           |           |
| 66                      |          |          |           |           |
| 70                      |          |          |           |           |
| 88                      |          |          |           |           |
| 100                     |          |          |           |           |
| 100                     |          |          |           |           |
| 110                     |          |          |           |           |
| 150                     |          |          |           |           |
| 150                     |          |          |           |           |
| 200                     |          |          |           |           |
| 200                     |          |          |           |           |
| 260                     |          |          |           |           |

# Small PCB footprint Higher packing density on the PCB



## Example 100 µF, 1100 V DC

- **B32320I** – 20 cm<sup>2</sup>  
Footprint 5.3 µF/cm<sup>2</sup>
- **Typical boxed shape** – 60 cm<sup>2</sup>  
Footprint 1.7 µF/cm<sup>2</sup>



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